

Amendments to the Claims:

Cancel claims 2 and 5-13, without prejudice or disclaimer.

The following listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (currently amended) A method of manufacturing a transparent substrate that is to have a transparent conductive film formed on a surface thereof, comprising:

controlling a surface smoothness of the surface of the transparent substrate to satisfy

$0 \text{ nm} \leq R_z \leq 4 \text{ nm}$; and

controlling a surface smoothness of a surface of the transparent conductive film to satisfy

$0 \text{ nm} \leq R_z \leq 8 \text{ nm}$,

wherein the controlling of the surface smoothness is carried out by omitting polishing of the surface of the transparent substrate.

2. (canceled)

3. (currently amended) The method of manufacturing a transparent substrate as claimed in claim [[2]] 1, wherein the surface of the transparent substrate is subjected to etching using an acidic aqueous solution containing hydrofluoric acid or an alkaline aqueous solution containing potassium hydroxide or sodium hydroxide.

4. (previously presented) The method of manufacturing a transparent substrate as claimed in claim 3, wherein after the etching has been carried out, the surface of the transparent substrate is subjected to alkaline washing comprising washing using an alkaline liquid.

5.-13 (canceled)

14.-30. (canceled)